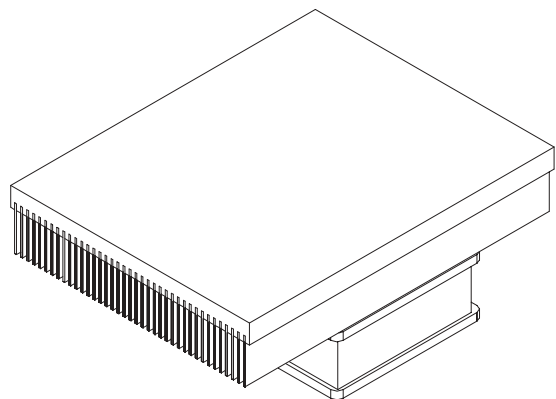
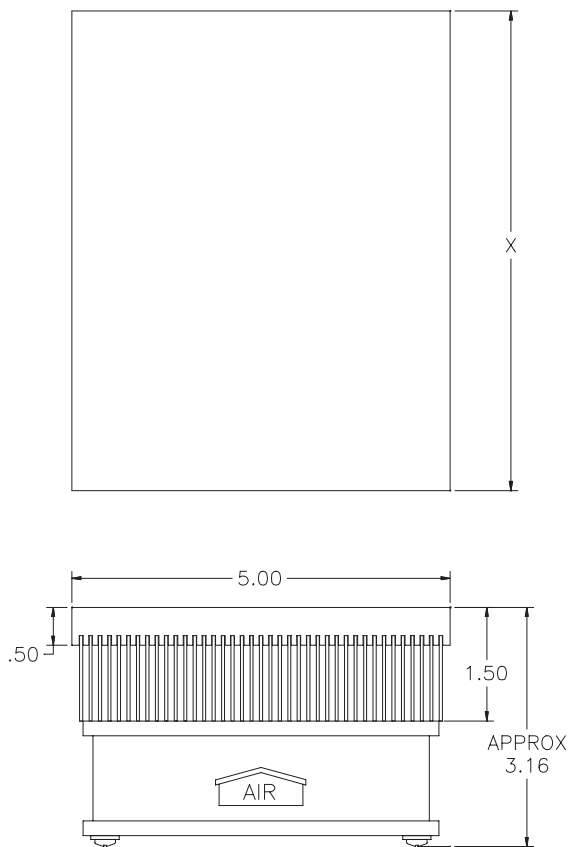


IMPINGEMENT COOLING HEAT SINKS

Available with ball bearing muffin XL fan. Ideal for IGBT and power MOSFET applications as well as diode and SCR bridges. Extremely low cost per watt. The impingement cooling allows modules to be mounted close together. This allows the IGBT s to operate at the same temperature, increasing system reliability. This also allows for shorter bus bars, resulting in lower circuit inductance.



POWER-PAK IMPINGEMENT COOLING		
MODEL #	CH6500	CH6600
Dimension X	5.0"	8.00"
Thermal Resistance	.1° C/W	.08° C/W

Thermal performance based on 100CFM fan(s). Mounting pattern shown fits standard muffin fan(s).